## GreenGuard® Technical Bulletin #7

Contribution To LEED<sup>™</sup> Credits

## Overview

The LEED  $^{\!\!\!\!\!\!\!\!^{M}}$  Green Building Rating System version 4.1 is a tool that enables a design professional to accumulate credits for a specific building based on meeting certain criteria relating to the use of environmentally preferable, sustainable and energy efficient building materials and systems. Kingspan GreenGuard® XPS Insulation Board can contribute to achieving LEED™ rating points in the categories listed below.

**XPS** Insulation Board

Source of Raw Materials: up to 2 point could be provided for Responsible Sourcing of Raw materials

- Use products sourced from at least three different manufacturers that meet at least one of the responsible sourcing and extraction criteria below for at least 15%, by cost, of the total value of permanently installed building products in the project (1 point).
- Recycled content is the sum of postconsumer recycled content plus one-half the pre-consumer recycled content, based on weiaht.

GreenGuard XPS products contain up to 20% of pre-consumer content

## Environmental Product Declarations

Environmental Product Declaration (EPD) (1 point)

Use at least 20 different permanently installed products sourced from at least five different manufacturers that meet one of the disclosure criteria below. (10 different permanently installed products from three different manufacturers for CS and Warehouses & Distribution Centers).



Please scan the QR code for the most recent product information

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